

UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

SAMSUNG ELECTRONICS CO., LTD.
Petitioner

v.

DAEDALUS PRIME LLC
Patent Owner

Case IPR2023-00534
Patent No. 10,319,812

JOINT MOTION TO TERMINATE

UPDATED EXHIBIT LIST

SAMSUNG-1001	U.S. Patent No. 10,319,812 to Webb, et al. (“the ’812 Patent”)
SAMSUNG-1002	Excerpts from the Prosecution History of the ’812 Patent (“the Prosecution History”)
SAMSUNG-1003	Declaration of David Kuan-Yu Liu
SAMSUNG-1004	U.S. Patent Pub. No. 2015/0054078 to Xie (“Xie”)
SAMSUNG-1005	U.S. Patent No. 9,397,217 to Tseng (“Tseng”)
SAMSUNG-1006	U.S. Patent Pub. No. 2012/0086055 to Anderson (“Anderson”)
SAMSUNG-1007	U.S. Patent No. 9,041,125 to Lin (“Lin”)
SAMSUNG-1008	U.S. Patent Pub. No. 2013/0026572 to Kawa (“Kawa”)
SAMSUNG-1009	U.S. Patent Pub. No. 2007/0080380 to Chang (“Chang”)
SAMSUNG-1010	U.S. Patent No. 9,324,790 to Akarvardar (“Akarvardar”)
SAMSUNG-1011	U.S. Patent No. 8,994,116 to Gan (“Gan”)
SAMSUNG-1012	U.S. Patent No. 11,037,923 to Bohr (“Bohr”)
SAMSUNG-1013	U.S. Patent No. 7,898,037 to Chuang (“Chuang”)
SAMSUNG-1014	U.S. Patent No. 9,166,053 to Kuo (“Kuo”)
SAMSUNG-1015	U.S. Patent Pub. No. 2013/0164924 to Shieh (“Shieh”)
SAMSUNG-1016	U.S. Patent No. 8,895,381 to Cheng (“Cheng”)
SAMSUNG-1017	U.S. Patent No. 9,196,613 to Basker (“Basker”)
SAMSUNG-1018	Robert H. Havemann and James A. Hutchby, “High-Performance Interconnects: An Integration Overview,” Proceedings of the IEEE, vol. 89, no. 5, pp. 586-601, May 2001

SAMSUNG-1019	Dick James, “Intel Ivy Bridge Unveiled – The First Commercial Tri-Gate, High-k, Metal-Gate CPU,” Proceedings of the IEEE 2012 Custom Integrated Circuits Conference, September 2012
SAMSUNG-1020	U.S. Patent No. 8,492,841 to Anderson (“Anderson-841”)
SAMSUNG-1021	U.S. Patent Pub. No. 2012/0037996 to Schultz (“Schultz”)
SAMSUNG-1022	U.S. Patent No. 8,952,424 to Herberholtz (“Herberholtz”)
SAMSUNG-1023	U.S. Patent Pub. No. 2017/0186882 to Koldiaev (“Koldiaev”)
SAMSUNG-1024	Reserved
SAMSUNG-1025	U.S. Patent No. 9,281,378 to Ching (“Ching”)
SAMSUNG-1026	U.S. Patent No. 6,894,357 to Guo (“Guo”)
SAMSUNG-1027	U.S. Patent No. 7,586,159 to Lee (“Lee”)
SAMSUNG-1028	U.S. Patent Pub. No. 2006/0220090 to Metz (“Metz”)
SAMSUNG-1029	U.S. Patent Pub. No. 2015/0200275 to Zhu (“Zhu”)
SAMSUNG-1030	U.S. Patent No. 8,637,931 to Basker (“Basker-931”)
SAMSUNG-1031	U.S. Patent No. 8,697,515 to Yin (“Yin”)
SAMSUNG-1032	Reserved
SAMSUNG-1033	Reserved
SAMSUNG-1034	U.S. Patent No. 7,632,745 to Chen (“Chen-745”)
SAMSUNG-1035	U.S. Patent No. 9,246,003 to Cheng (“Cheng”)
SAMSUNG-1036	U.S. Patent No. 7,592,675 to Liaw (“Liaw”)
SAMSUNG-1037	U.S. Patent No. 9,214,529 to Chang (“Chang-529”)
SAMSUNG-1038	U.S. Patent Pub. No. 2011/0031552 to Iwamatsu (“Iwamatsu”)

SAMSUNG-1039	U.S. Patent No. 9,461,143 to Pethe (“Pethe”)
SAMSUNG-1040	U.S. Patent No. 8,901,665 to Kelly (“Kelly”)
SAMSUNG-1041	U.S. Patent No. 6,720,619 to Chen (“Chen-619”)
SAMSUNG-1042-1049	Reserved
SAMSUNG-1050	Daedalus Prime LLC v. Samsung Electronics Co., Ltd. and Samsung Electronics America, Inc. and Taiwan Semiconductor Manufacturing Company Limited and TSMC North America, Complaint, ITC Inv. No. 337-TA-1336 (ITC) (“ITC Complaint”)
SAMSUNG-1051	ITC Complaint: Public Exhibit 12
SAMSUNG-1052	ITC Complaint: Public Exhibit 39
SAMSUNG-1053	ITC Complaint: Public Exhibit 45
SAMSUNG-1054	Daedalus Prime LLC v. Samsung Electronics Co., Ltd. et al., 2:22-cv-00352, E.D. Tex.
SAMSUNG-1055	Settlement Agreement

The Parties in this case have reached a settlement that addresses this proceeding. The Parties therefore contacted the Board on June 1, 2023, to inform the Board of the settlement and request instructions regarding termination of this proceeding. In accordance with the Board's email instructions received on June 2, 2023, the Parties hereby jointly submit this motion to terminate. The Parties respectfully request that the Board terminate IPR2023-00534 with prejudice.

Pursuant to 35 U.S.C. § 317(b), 37 C.F.R. § 42.74, and the Board's e-mail, the Parties have concurrently filed the Settlement Agreement as Exhibit 1055. The Parties state that there are no other agreements, oral or written, between the Parties made in connection with, or in contemplation of, the termination of the proceeding. The Parties have concurrently filed a joint request to treat the Settlement Agreement as confidential business information pursuant to 37 C.F.R. § 42.74(c), consistent with the provisions of the Agreement.

Respectfully submitted,

Dated June 13, 2023

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CERTIFICATE OF SERVICE

Pursuant to 37 CFR § 42.6(e), the undersigned certifies that on June 13, 2023, a complete and entire copy of this Joint Motion to Terminate and Exhibit 1055 were provided by email, to the Patent Owner, by serving the correspondence addresses of record as follows:

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